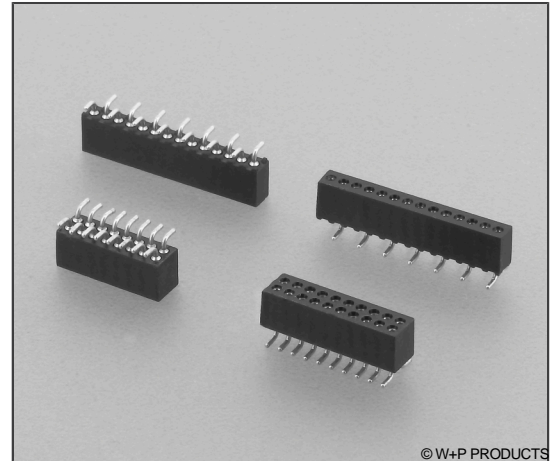


## SMT-Präzisions-Buchsenleisten RM 1,27mm, stehend, 1-/2-reihig SMT Precision Female Headers, 1.27mm Pitch, Vertical, Single/Double Row

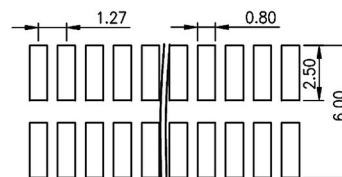
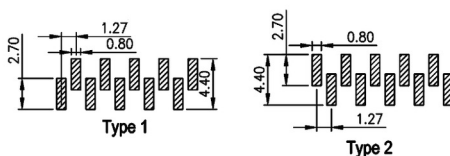
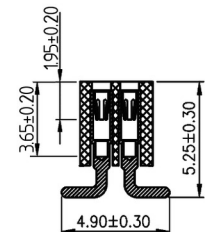
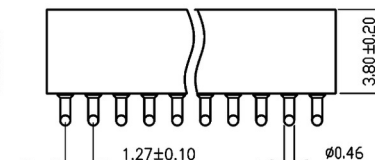
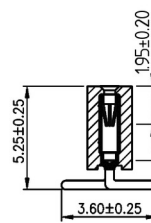
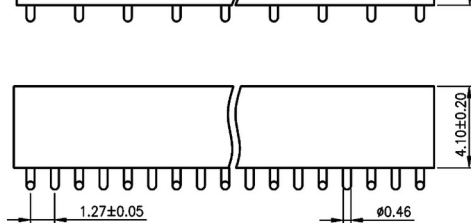
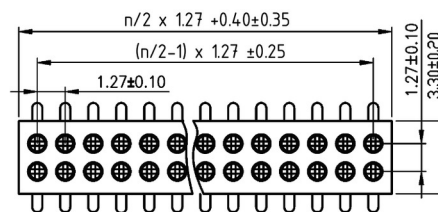
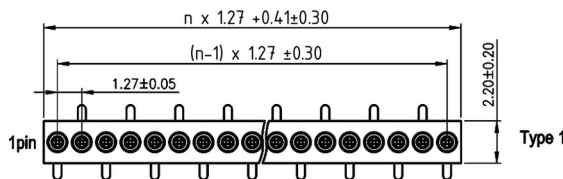
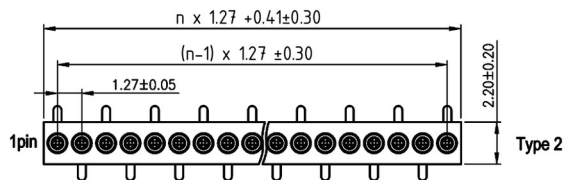
### Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Hülse: Messing gedreht Feder: 6-Lamellen-Clip, Beryllium-Kupfer <i>Sleeve: screw machined brass Clip: 6-Finger-Clip, Beryllium-Copper</i>
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm) <i>Acc. to options (see below), over Ni (1.3 ... 2.5µm)</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ <i>&lt; 20 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ <i>&gt; 1000 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500 V RMS <i>500 V RMS</i>
Nennspannung <i>Voltage Rating</i>	100 V RMS / 150 V DC <i>100 V RMS / 150 V DC</i>
Nennstrom <i>Current Rating</i>	1 A <i>1 A</i>
Temperaturbereich <i>Temperature Range</i>	-55 °C ... +125 °C <i>-55 °C ... +125 °C</i>
Verarbeitung <i>Processing</i>	Kurzes Reflow-Lötverfahren <i>Fast reflow soldering</i>



© W+P PRODUCTS

Einsetzbar für Rundstifte Ø0,35-0,50mm.  
Contacts accept Ø0.35-0.50mm round pins.



<b>Series</b>	<b>Contacts*</b>	<b>Rows*</b>	<b>Sleeve Plating</b>	<b>Clip Plating</b>	<b>Packaging*</b>
<b>1551C</b>	<b>020</b>	<b>2</b>	<b>50</b>	<b>00</b>	<b>PPST</b>
	003-050 Einreihig Single row 004-100 Zweireihig Double row	1 Einreihig B1 Single row B1 2 Einreihig B2 Single row B2 3 Zweireihig Double row	50 Hülse verzinkt Tin plated sleeve	00 Feder vergoldet Gold plated clip	ST PPST PPTR (Option)

**Lieferformen / Packaging Options:**  
**ST** In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads  
**PPST** In Stangen mit P&P-Pads / In tubes with P&P-Pads  
**PPTR (Option)** Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
 \* This is an **order example** - please replace by your specifications.

## Informationen zum kurzen Reflow-Lötverfahren Fast Profile Reflow Soldering Information

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150°C
Temperatur Maximum $T_{Smax}$	200°C
Dauer $T_{Smin} - T_{Smax}$	120-150s
Temperatur Lötbereich $T_L$	230°C
Verweildauer oberhalb $T_L$	60s max.
Ramp-Up Rate $T_{Smax} - T_P$	max. 1,5°C / s
Höchsttemperatur $T_P$	260°C max.
Dauer Höchsttemperatur	5-10s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	3°C / s
Dauer 25°C - Höchsttemperatur $T_P$	Max. 4,5min

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150°C
Maximum Temperatur $T_{Smax}$	200°C
Duration $T_{Smin} - T_{Smax}$	120-150s
Soldering Range Temperature $T_L$	230°C
Duration above $T_L$	60s max.
Ramp-Up Rate $T_{Smax} - T_P$	max. 1.5°C / s
Peak Temperature $T_P$	260°C max.
Duration Peak Temperature	5-10s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	3°C / s
Duration 25°C - Peak Temp. $T_P$	Max. 4.5min

